

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Allen McTeer

Application No.: Not Yet Assigned

Group Art Unit: 2822

Filed: September 5, 2003

Examiner: Not yet Assigned

For: A MULTI-LAYERED COPPER BOND PAD  
FOR AN INTEGRATED CIRCUIT (AS  
AMENDED)

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**FIRST PRELIMINARY AMENDMENT**

**Box Non-Fee Amendment**

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

**In the Specification**

Page 2, after the title, please insert --This application is a continuation of Application Ser. No. 10/079,858, filed February 22, 2002, which in turn is a divisional of Application Ser. No. 09/532,087, filed on March 21, 2000, the disclosure of both of which are incorporated by reference herein.--

**In the Title**

Please change the current title with – A MULTI-LAYERED COPPER BOND PAD FOR AN INTEGRATED CIRCUIT --.